

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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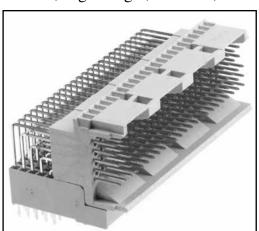




# 3M<sup>™</sup> MetPak<sup>™</sup> 2-FB Inverse Header

2 mm 5-Row, Right Angle, Elevated, Solder Tail

MP2 Series



- Elevated connector for offset coplanar/end-to-end stacking
- Ideal for low profile IU boxes
- Ideal for "pizza box" applications
- Ideal for hot swapping applications
- 16 mm to 18.5 mm high profile stacking
- Mates with MP2-SXXXG sockets
- Prevents removing top cover in rack applications
- Footprint compatible with standard Futurebus+®
- See the Regulatory Information Appendix (RIA) in the "RoHS compliance" section of www.3Mconnectors.com for compliance information (RIA E1 & C1 apply)

Date Modified: September 17, 2013

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### **Physical**

**Insulation:** 

Material: High Temp LCP Flammability: UL 94V-0 Color: Beige

**Contact:** 

Material: Copper Alloy

**Plating:** 

Underplating: 50 μ" [1.27 μm] Nickel Wiping Area: See Ordering Information Solder Tails: See Ordering Information

### **Electrical**

**Current Rating:** Signal: 1.5 A – All contacts simultaneously

Insulation Resistance:  $10^3 M\Omega$ Withstanding Voltage:  $1000 V_{MC}$ 

#### **Environmental**

**Temperature Rating:** -55°C to +125°C

**Process Temperature Rating:** 260°C (Profile per J-STD-020C)

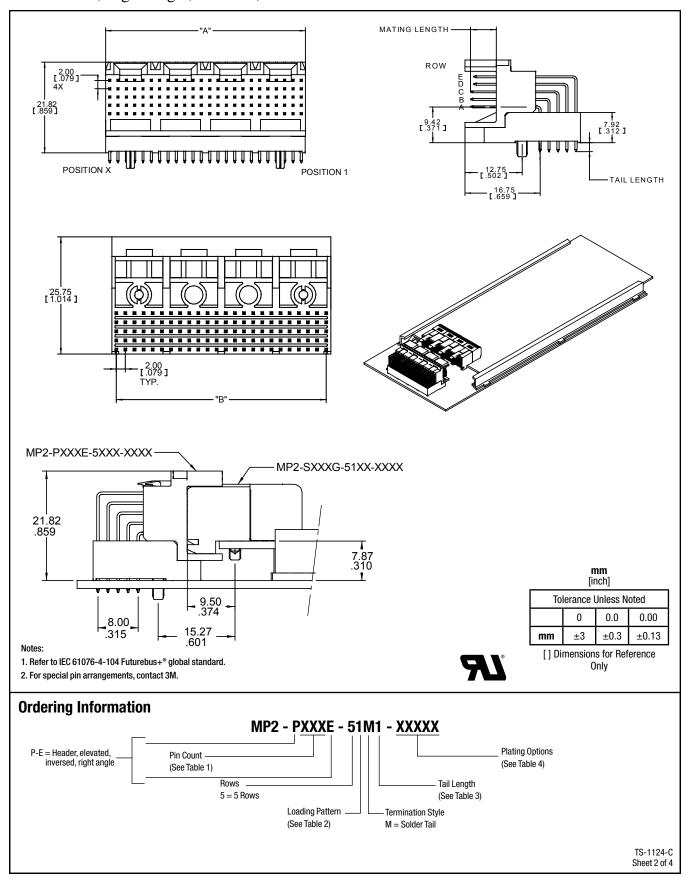
**Moisture Sensitivity Level:** 1 (per J-STD-020C)

MetPak is a trademark of 3M Company.

Futurebus+ is a registered trademark of the Institute of Electrical and Electronic Engineers, Inc. (IEEE)

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**MP2 Series** 



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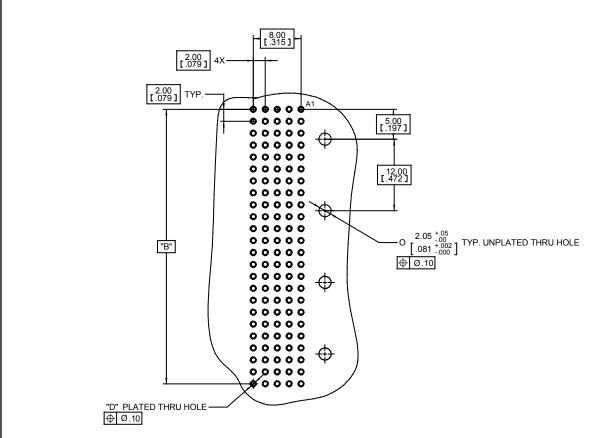
Table 1 - Connector & Row Lengths					
Pin Count Dim. "A" mm [inch]		Dim "B" mm [inch]	Rows		
120	47.95 [1.888]	46.00 [1.811]	5		
240	95.95 [3.778]	94.00 [3.701]	5		

Table 2 - Mate Length						
Loading Pattern Code	Description	Mate Length Row A	Mate Length Row B	Mate Length Row C	Mate Length Row D	Mate Length Row E (5-Row Prod. Only)
1	All Positions Filled	5.00 [0.197]	5.00 [0.197]	5.00 [0.197]	5.00 [0.197]	5.00 [0.197]

Table 3 - Tail Length						
Loading Pattern Code	Description	Tail Length Row A	Tail Length Row B	Tail Length Row C	Tail Length Row D	Tail Length Row E
1	All Positions Filled	3.13 [0.123]	3.13 [0.123]	3.13 [0.123]	2.38 [0.094]	2.38 [0.094]

Table 4 - Plating			
Plating Suffix Plating Composition			
KR (RIA E1 & C1 apply)	0.76 μm [30 μ"] Min. Au Contact Area 2.54 μm [100 μ"] Min. Matt Whisker Mitigating Sn Tail Area 1.27 μm [50 μ"] Min. Ni all over		
LR (RIA E1& C1 apply)	0.08 μm [3 μ"] Min. Au Contact Area 0.67 μm [27 μ"] Min. PdNi Contact Area 2.54 μm [100 μ"] Min. Matt Whisker Mitigating Sn Tail Area 1.27 μm [50 μ"] Min. Ni all over		

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RECOMMENDED PCB HOLE MOUNTING PATTERN

Table 5 - HOLE PLATING FINISHES						
HOLE	Finished Dia. MM [in]	Cu Thickness [mm [in]	Immersion Matte Sn Thickness microns [µ"]	Electrolytic Au Thickness microns [µ"]	OSP ENTEK Thickness microns [µ"]	Drilled Hole Dia. mm [in]
"D"	0.700-0.800 [.02760315]	0.025-0.045 [0.001-0.002]	0.5 - 2.5 [20 - 100]	0.1 - 0.5 [4 - 20]	0.2 - 0.5 [8 - 20]	0.830-0.860 [.0330- .0340] or 0.85 mm [#66] TWIST DRILL

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the legal theory asserted.

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